

12/11/00

RECC



HEET

OMB No. 0651-0011 (exp. 4/94)

101566032

Tab settings >>>

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Joseph W. Cowan

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: LSI Logic Corporation

Internal Address: _____

Street Address: 1551 McCarthy Boulevard

City: Milpitas State: CA ZIP: 95035

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

Assignment

Merger

Security Agreement

Change of Name

Other _____

Execution Date: December 8, 2000

4. Application number(s) or patent number(s):

91735085

If this document is being filed together with a new application, the execution date of the application is: 12/08/00

A. Patent Application No.(s)

B. Patent No.(s)

12/14/2000 BNGUYEN1 00000074 09735085

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40.00 OP

Additional numbers attached? Yes No

5. Name and address of Party to whom correspondence concerning document should be mailed:

Name: John R. Ley

Internal Address: _____

Street Address: Suite 610
5299 DTC Boulevard

City: Englewood State: CO ZIP: 80111-3327

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

John R. Ley
Name of Person Signing

[Signature]
Signature

December 11, 2000
Date

Total number of pages including cover sheet, attachments, and document: 3

ASSIGNMENT OF INVENTION

Docket Number: 99-195

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged,

I, the undersigned, Joseph W. Cowan

does hereby sell, assign, and transfer to:

LSI LOGIC CORPORATION, a corporation of Delaware, having a place of business at 1551 McCarthy Boulevard, Milpitas, California 95035, ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent,

which has been executed by the undersigned concurrently herewith,

and which is entitled:

INTERCONNECTOR AND METHOD OF CONNECTING PROBES TO A DIE FOR FAILURE ANALYSIS

in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said

